

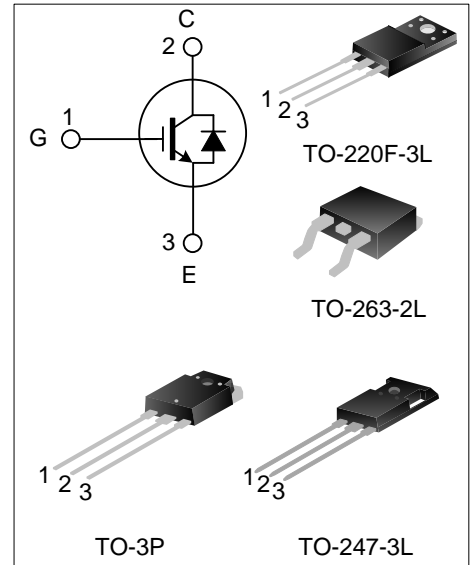
20A, 600V FIELD STOP IGBT

DESCRIPTION

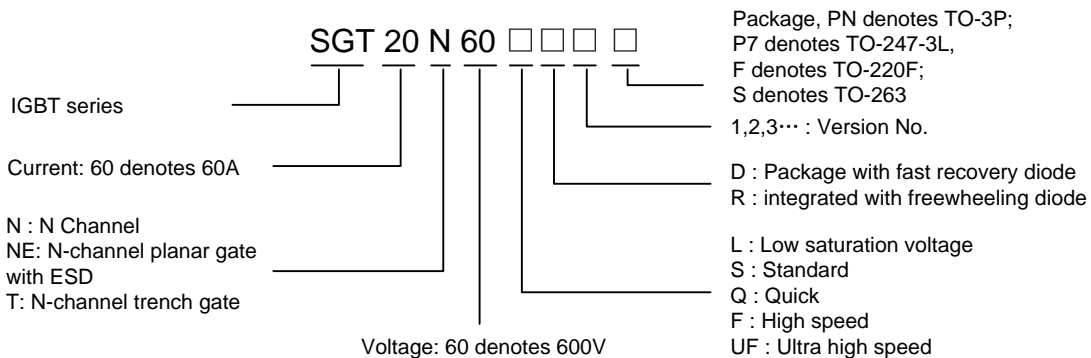
SGT20N60FD1PN/P7/F/S using Field Stop IGBT technology, offers the optimum performance for induction Heating, UPS, SMPS and PFC application.

FEATURES

- ◆ 20A, 600V, $V_{CE(sat)(typ.)}=2.0V@I_C=20A$
- ◆ Low conduction loss
- ◆ Fast switching
- ◆ High input impedance



NOMENCLATURE



ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing
SGT20N60FD1PN	TO-3P	20N60FD1	Pb free	Tube
SGT20N60FD1P7	TO-247-3L	20N60FD	Pb free	Tube
SGT20N60FD1F	TO-220F-3L	20N60FD1F	Pb free	Tube
SGT20N60FD1S	TO-263-2L	20N60FD1S	Pb free	Tube

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Parameter	Symbol	Ratings				Units
		SGT20N60 FD1PN	SGT20N60 FD1P7	SGT20N60 FD1F	SGT20N60 FD1S	
Collector to Emitter Voltage	V _{CE}	600				V
Gate to Emitter Voltage	V _{GE}	±20				V
Collector Current	I _C	40				A
		20				
Pulsed Collector Current	I _{CM}	60				A
Power Dissipation(T _C =25°C) -Derate above 25°C	P _D	155	167	38	195	W
		1.24	1.33	0.25	1.56	W/°C
Operating Junction Temperature Range	T _J	-55~+150				°C
Storage Temperature Range	T _{stg}	-55~+150				°C

THERMAL CHARACTERISTICS

Parameter	Symbol	Ratings				Units
		SGT20N60 FD1PN	SGT20N60 FD1P7	SGT20N60 FD1F	SGT20N60 FD1S	
Thermal Resistance, Junction to Case (IGBT)	R _{θJC}	0.79	0.75	3.95	0.64	°C/W
Thermal Resistance, Junction to Case (FRD)	R _{θJC}	2.7	2.24	5.2	3.07	°C/W
Thermal Resistance, Junction to Ambient	R _{θJA}	40	40	62.5	30	°C/W

ELECTRICAL CHARACTERISTICS OF IGBT (T_C = 25°C unless otherwise noted)

Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Units
Collector to Emitter Breakdown Voltage	BV _{CE}	V _{GE} =0V, I _C =100μA	600	--	--	V
C-E Leakage Current	I _{CES}	V _{CE} =600V, V _{GE} =0V	--	--	200	μA
G-E Leakage Current	I _{GES}	V _{GE} =20V, V _{CE} =0V	--	--	±400	nA
G-E Threshold Voltage	V _{GE(th)}	I _C =250μA, V _{CE} =V _{GE}	4.0	5.0	6.5	V
Collector to Emitter Saturation Voltage	V _{CE(sat)}	I _C =20A, V _{GE} =15V	--	2.0	2.7	V
		I _C =20A, V _{GE} =15V, T _C =125°C	--	2.3	--	V
Input Capacitance	C _{ies}	V _{CE} =30V V _{GE} =0V f=1MHz	--	916	--	pF
Output Capacitance	C _{oes}		--	108	--	
Reverse Transfer Capacitance	C _{res}		--	26	--	
Turn-On Delay Time	T _{d(on)}	V _{CE} =400V	--	15	--	ns

Rise Time	T_r	$I_C=20A$ $R_g=10\Omega$ $V_{GE}=15V$ Inductive Load	--	45	--	
Turn-Off Delay Time	$T_{d(off)}$		--	67	--	
Fall Time	T_f		--	129	--	
Turn-On Switching Loss	E_{on}	Inductive Load	--	0.898	--	mJ
Turn-Off Switching Loss	E_{off}		--	0.336	--	
Total Switching Loss	E_{st}		--	1.234	--	
Total Gate Charge	Q_g	$V_{CE} = 300V, I_C=20A,$ $V_{GE} = 15V$	--	57	--	nC
Gate to Emitter Charge	Q_{ge}		--	11	--	
Gate to Collector Charge	Q_{gc}		--	26	--	

ELECTRICAL CHARACTERISTICS OF FRD ($T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Units
Diode Forward Voltage	V_{FM}	$I_F = 12A, T_C=25^\circ C$	--	1.9	2.6	V
		$I_F = 12A, T_C=125^\circ C$	--	1.5	--	
Diode Reverse Recovery Time	T_{rr}	$I_{ES} = 12A, di_{ES}/dt = 200A/\mu s$	--	32	--	ns
Diode Reverse Recovery Charge	Q_{rr}	$I_{ES} = 12A, di_{ES}/dt = 200A/\mu s$	--	74	--	nC

TYPICAL CHARACTERISTIC CURVES

Figure 1. Typical Output Characteristics (25°C)

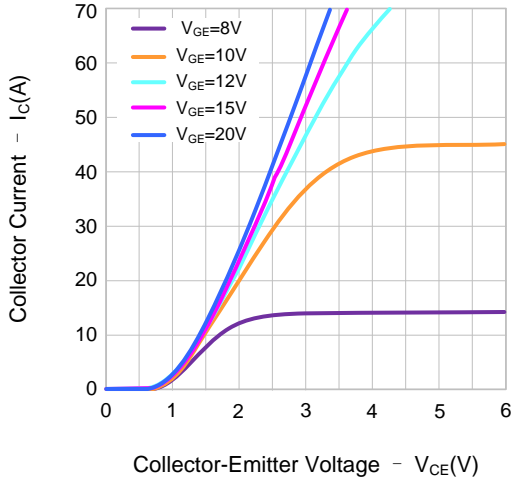


Figure 2. Typical Output Characteristics (125°C)

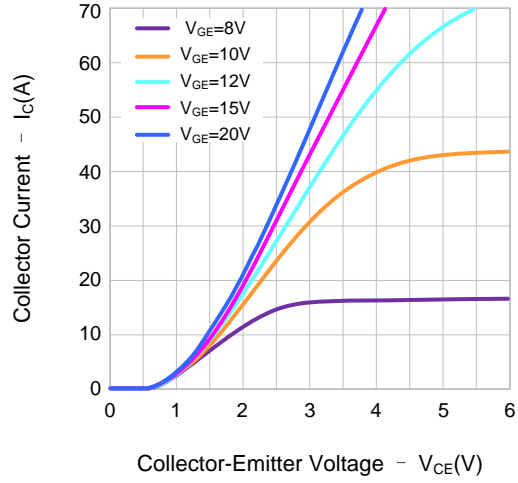


Figure 3. Typical Saturation Voltage Characteristics

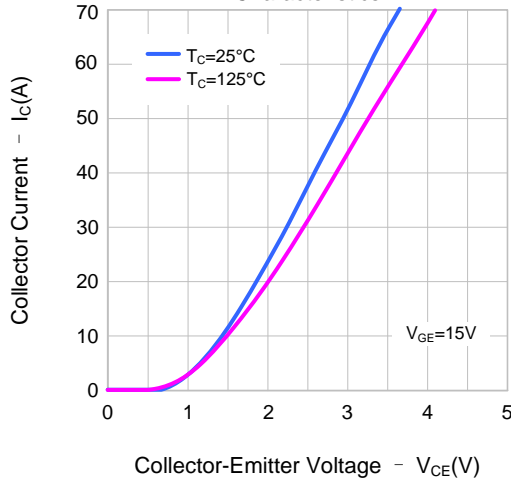
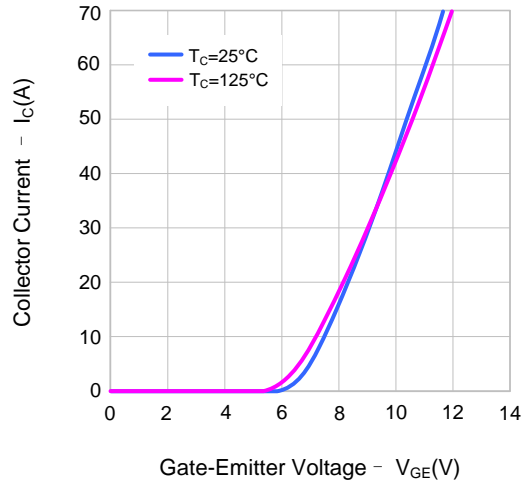


Figure 4. Transmission Characteristics



TYPICAL CHARACTERISTIC CURVES(continued)

Figure 5. Capacitance Characteristics

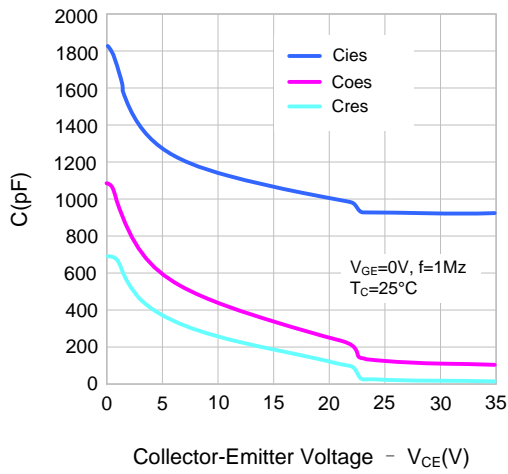


Figure 6. Gate Charge Characteristics

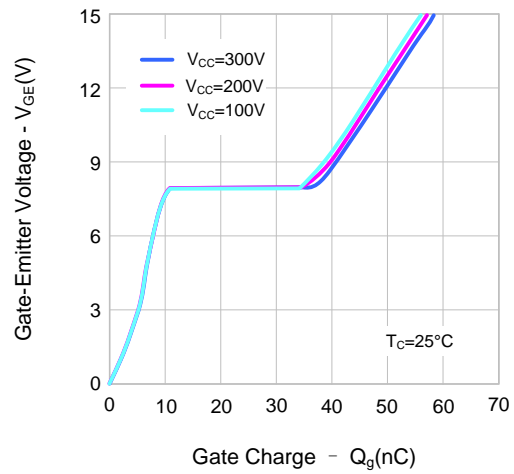


Figure 7. Turn-on Characteristics vs. Gate Resistance

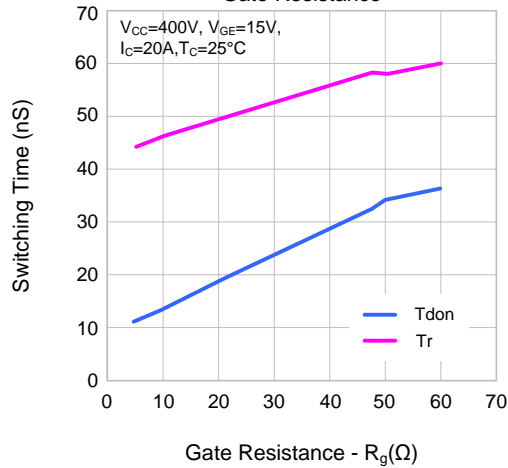


Figure 8. Turn-off Characteristics vs. Gate Resistance

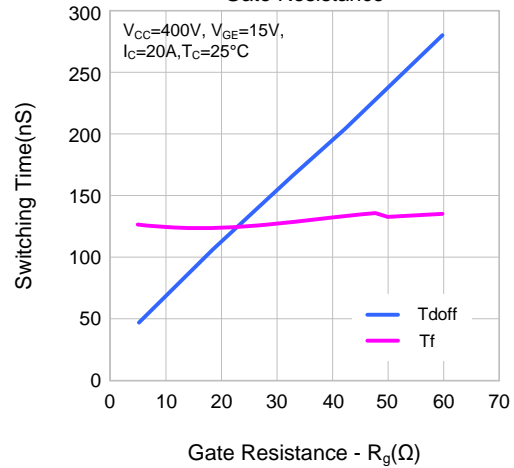


Figure 9. Switching Loss vs. Gate Resistance

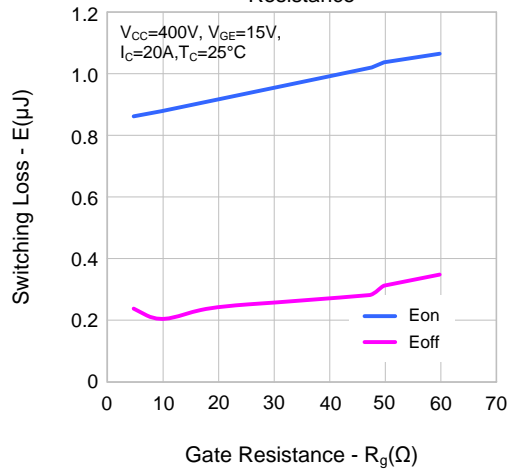
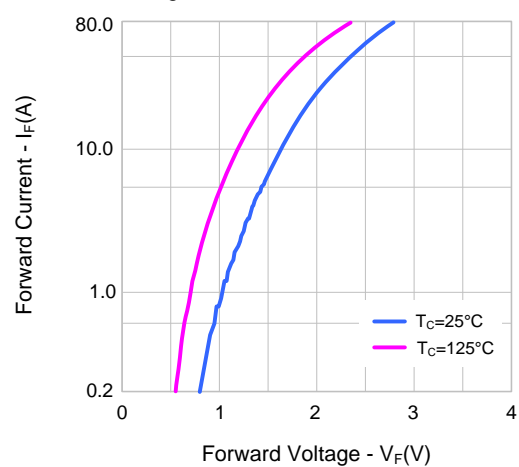


Figure 10. Forward Characteristics



TYPICAL CHARACTERISTIC CURVES(continued)

Figure 11-1. Max. Safe Operating Area(SGT20N60FD1PN)

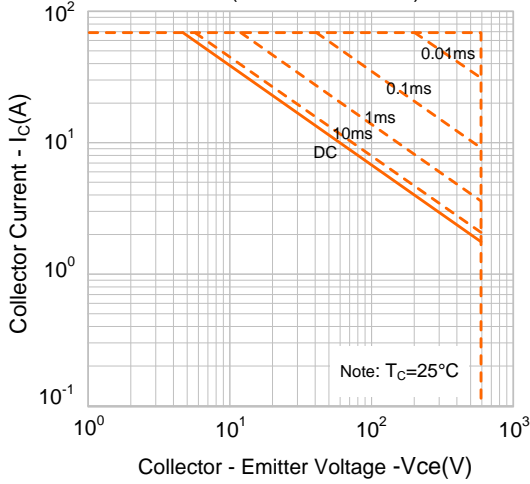


Figure 11-2. Max. Safe Operating Area(SGT20N60FD1P7)

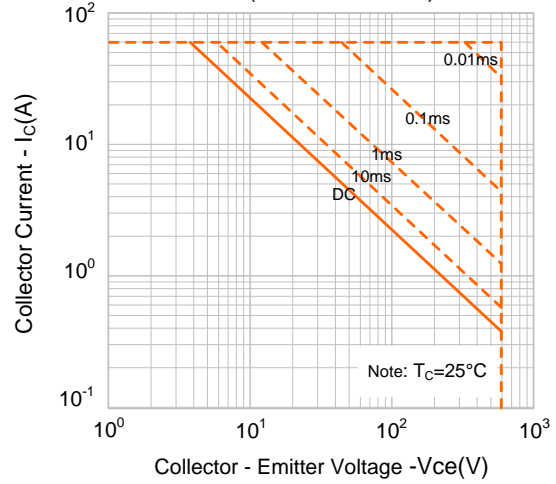


Figure 11-3. Max. Safe Operating Area(SGT20N60FD1F)

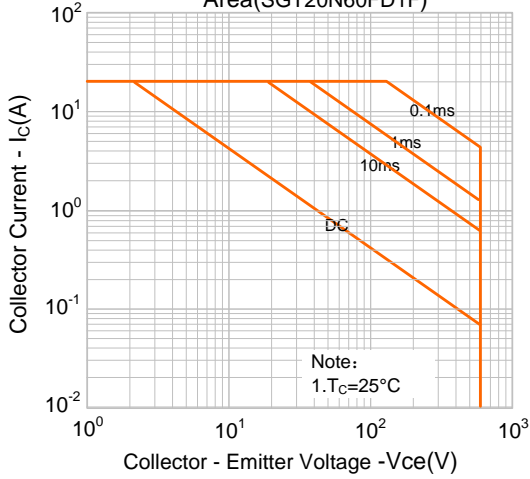
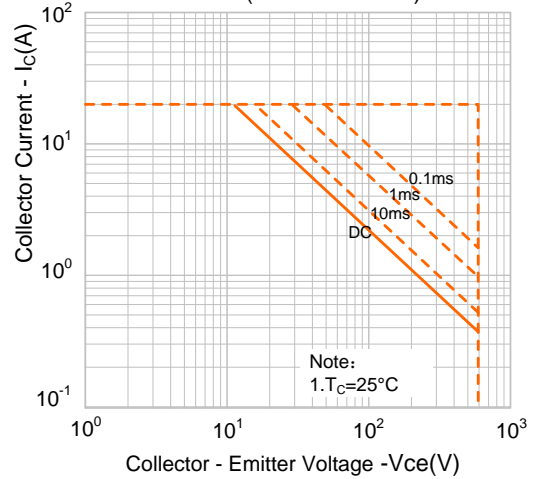
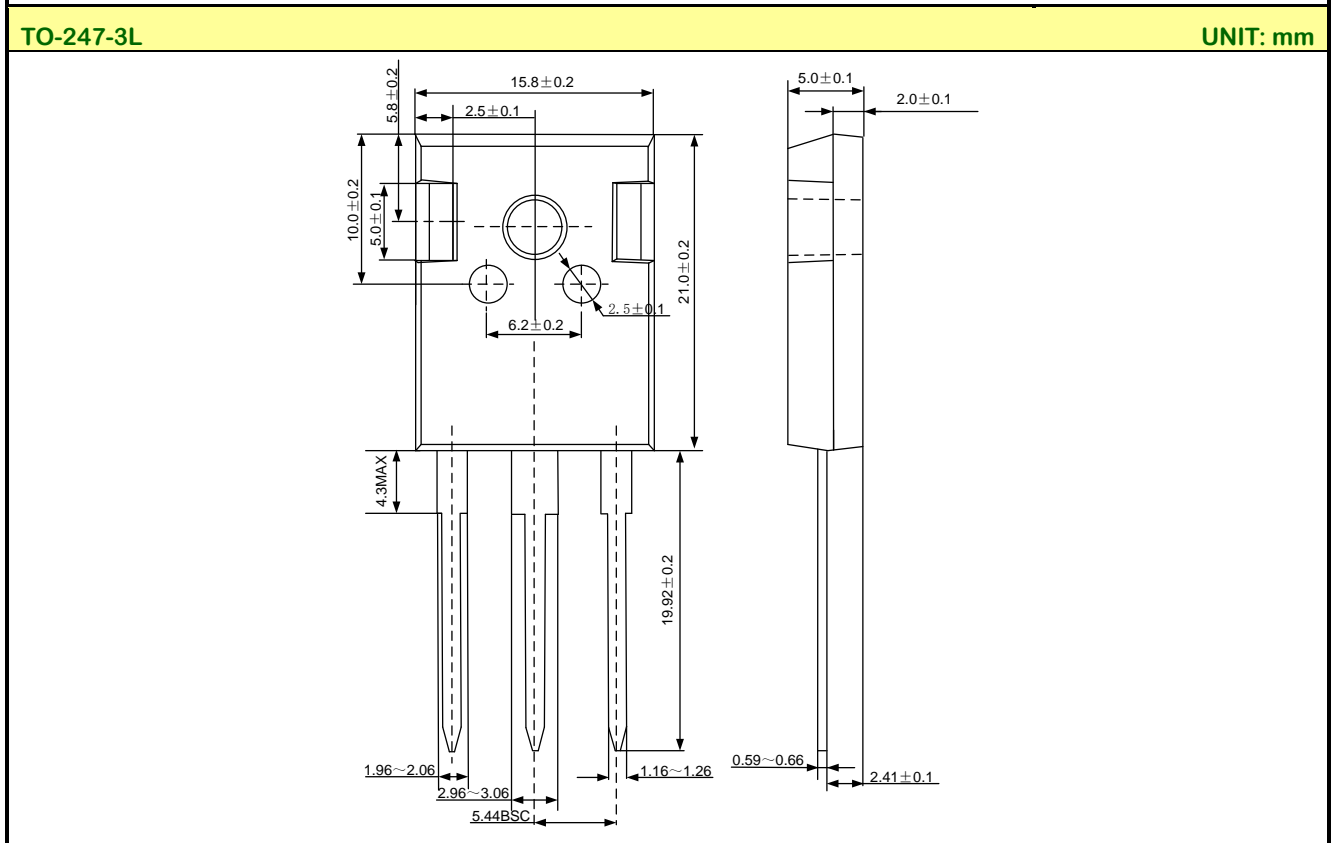
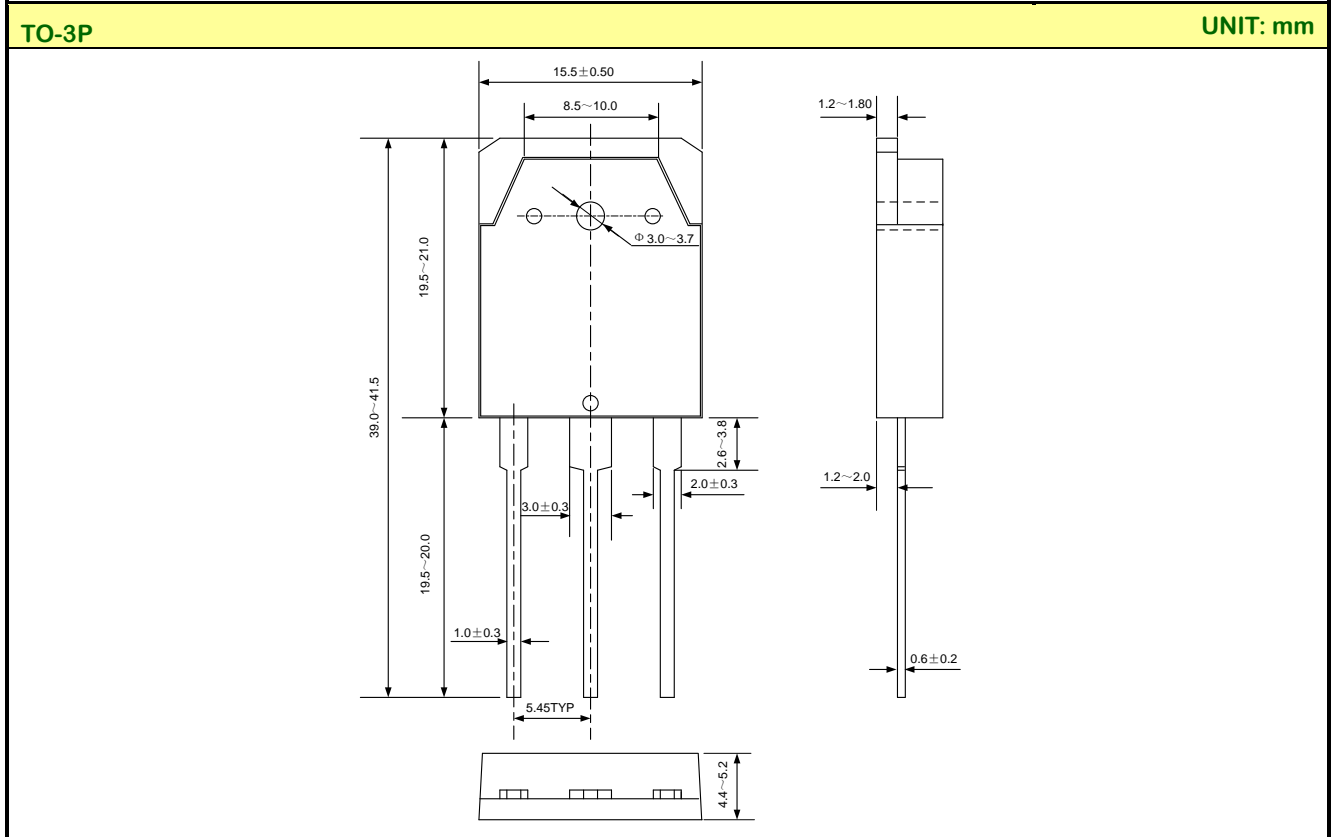


Figure 11-4. Safe Operating Area(SGT20N60FD1S)

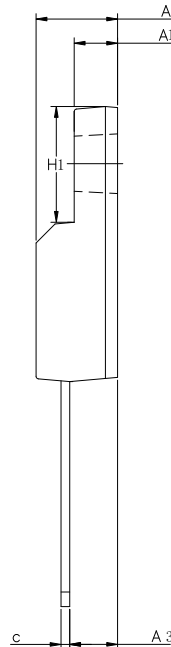
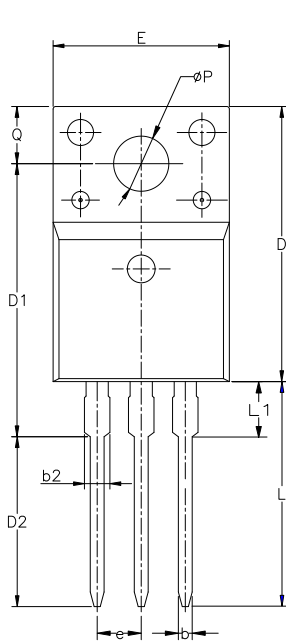


PACKAGE OUTLINE



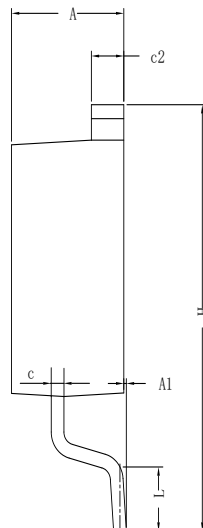
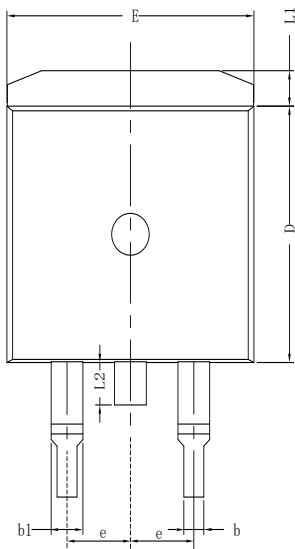
PACKAGE OUTLINE(continued)

TO-220F-3L 单位: mm



SYMBOL	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.70	0.80	0.90
b2	—	—	1.47
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	15.30	15.75	16.30
D2	9.30	9.80	10.30
E	9.73	10.16	10.36
e	2.54BCS		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	/	/	3.50
øP	3.00	3.18	3.40
Q	3.05	3.30	3.55

TO-263-2L 单位: mm



SYMBOL	MIN	NOM	MAX
A	4.30	4.57	4.72
A1	0	0.10	0.25
b	0.71	0.81	0.91
c	0.30	---	0.60
c2	1.17	1.27	1.37
D	8.50	---	9.35
E	9.80	---	10.45
e	2.54BSC		
H	14.70	---	15.75
L	2.00	2.30	2.74
L1	1.12	1.27	1.42
L2	---	---	1.75

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Part No.:	SGT20N60FD1PN/P7/F/S	Document Type:	Datasheet
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Rev.: 1.3

Revision History:

1. Add the package information of TO-263-2L
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Rev.: 1.2

Revision History:

1. Add the package information of TO-220F-3L
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Rev.: 1.1

Revision History:

1. Add the package information of TO-247-3L
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Rev.: 1.0

Revision History:

1. First release
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